

#### **General Description**

The WSR3090 is the highest performance trench N-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSR3090meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

#### **Absolute Maximum Ratings**

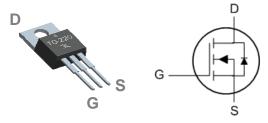
#### **Product Summery**

BVDSS	RDSON	ID
30V	4.5mΩ	90A

#### Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

#### **TO-220 Pin Configuration**



	Rating				
Symbol	Parameter	10s	Steady State	Units	
V <sub>DS</sub>	Drain-Source Voltage		30		
V <sub>GS</sub>	Gate-Source Voltage	=	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		90	А	
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>		60	А	
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	27	17	А	
I <sub>D</sub> @T <sub>A</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	23	14.5	А	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> 160		160	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup> 252		mJ		
I <sub>AS</sub>	Avalanche Current	48		А	
P₀@T₀=25℃	Total Power Dissipation <sup>4</sup> 53		W		
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	6	2.0	W	
T <sub>STG</sub>	Storage Temperature Range	-55	-55 to 175		
TJ	Operating Junction Temperature Range	-55	to 175	°C	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>eja</sub>	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>		62	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)		25	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		2.8	°C/W



**WSR3090** 

**N-Ch MOSFET** 

#### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.028		V/℃
Б	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		4.5	5.5	
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.8	9	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.0	1.5	2.5	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , I <sub>D</sub> =250uA		-6.16		mV/°C
	Drain Source Lookage Current	$V_{\text{DS}}\text{=}24V$ , $V_{\text{GS}}\text{=}0V$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			1	– uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		43		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7	3.1	Ω
Qg	Total Gate Charge (4.5V)			20	28	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		7.6	10.6	nC
Q <sub>gd</sub>	Gate-Drain Charge			7.2	10.1	
T <sub>d(on)</sub>	Turn-On Delay Time			11	15.6	
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =15A		15	27	
T <sub>d(off)</sub>	Turn-Off Delay Time			37.3	74.6	ns
T <sub>f</sub>	Fall Time			10.6	21.2	
Ciss	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		2295		
C <sub>oss</sub>	Output Capacitance			570		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			210		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =24A	63			mJ

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>				35	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			160	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1	V
t <sub>rr</sub>	Reverse Recovery Time			30		nS
Qrr	Reverse Recovery Charge	IF=30A , dl/dt=100A/ $\mu s$ , T $_{J}$ =25 $^{\circ}C$		24		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25V, V_{\text{GS}}\text{=}10V, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}24\text{A}$ 

4.The power dissipation is limited by 175  $^\circ\!\!\mathrm{C}$  junction temperature

5. The Min. value is 100% EAS tested guarantee.

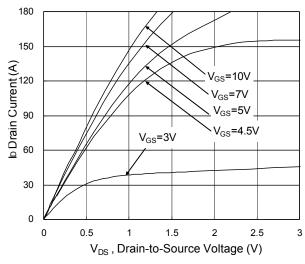
6.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

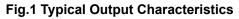


# WSR3090

#### **N-Ch MOSFET**

#### **Typical Characteristics**





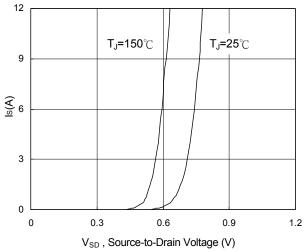


Fig.3 Forward Characteristics of Reverse

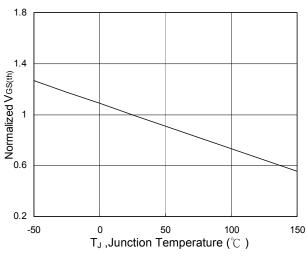


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

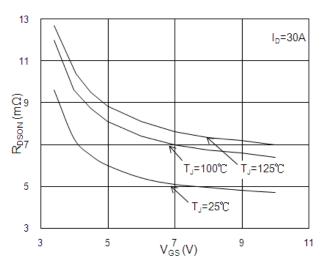


Fig.2 On-Resistance vs. G-S Voltage

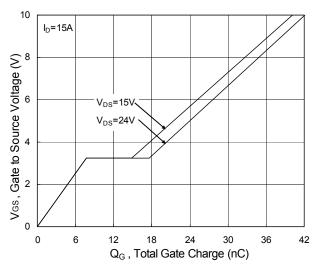


Fig.4 Gate-Charge Characteristics

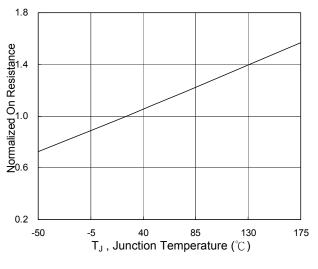


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>

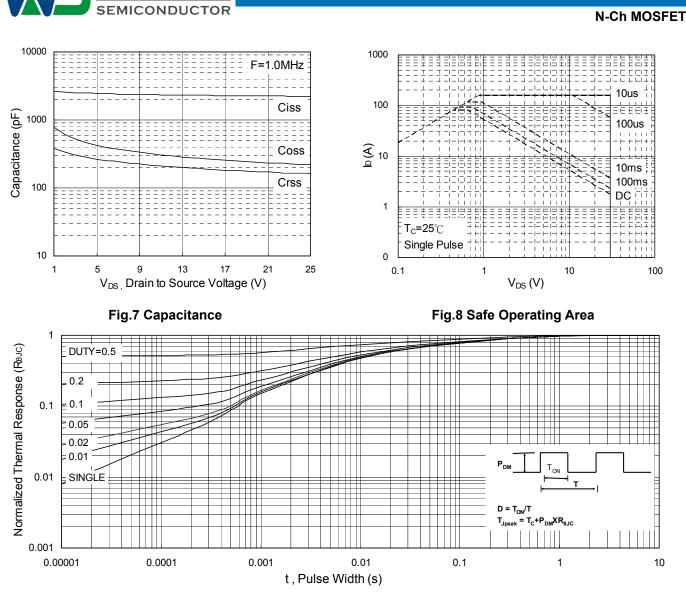
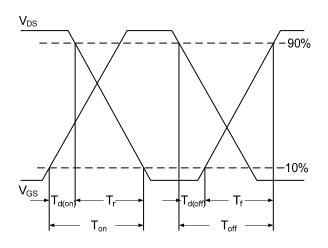


Fig.9 Normalized Maximum Transient Thermal Impedance



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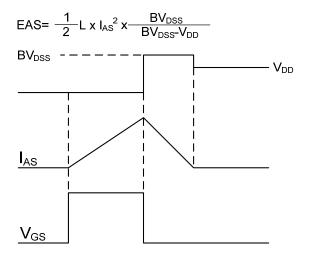


Fig.11 Unclamped Inductive Switching Waveform

**WSR3090** 



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